

4

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D

D

C

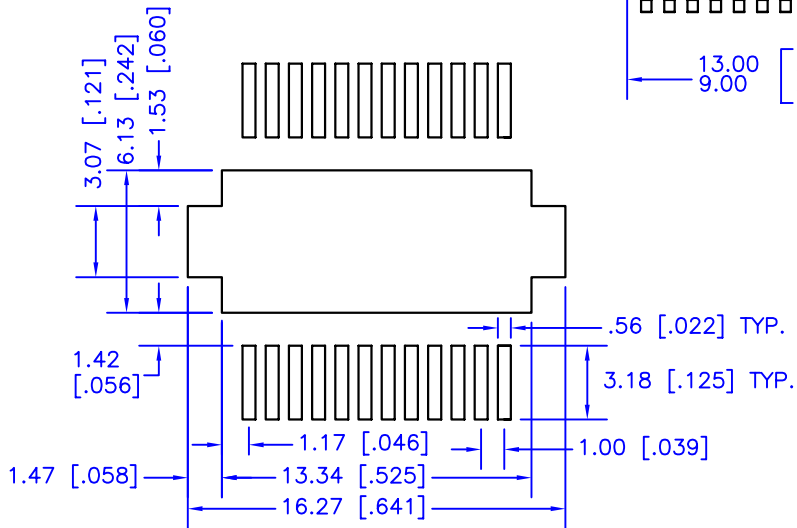
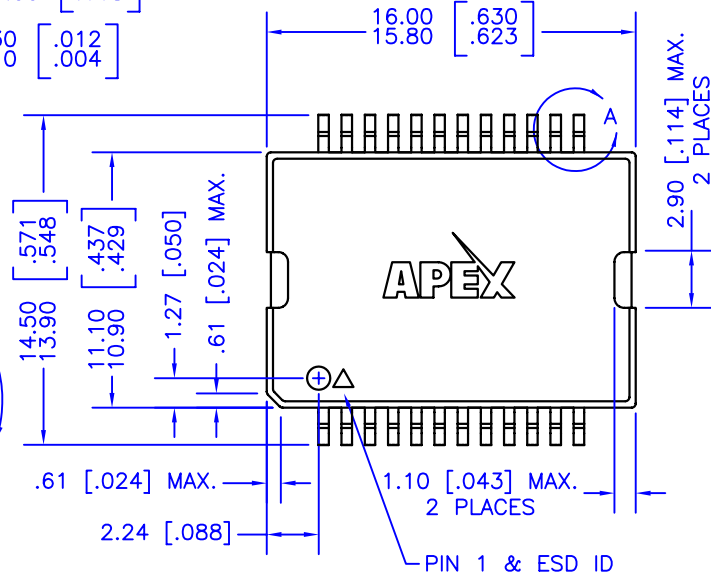
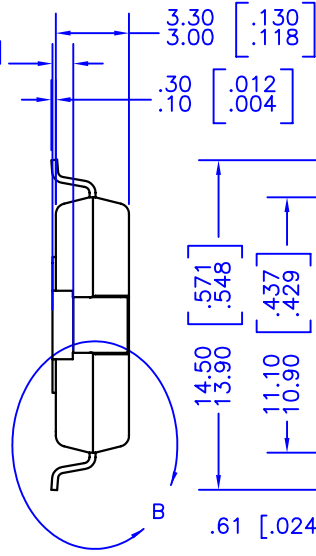
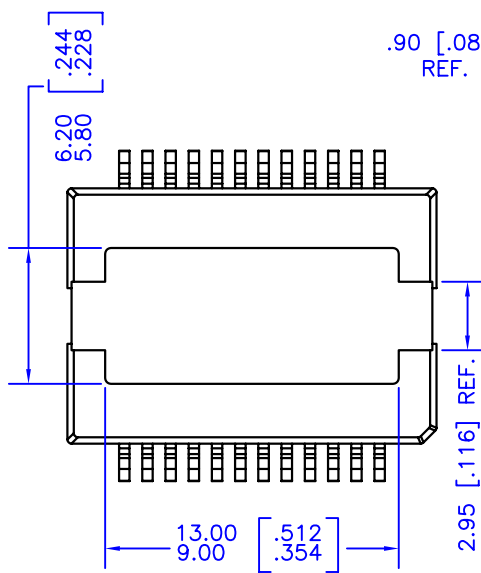
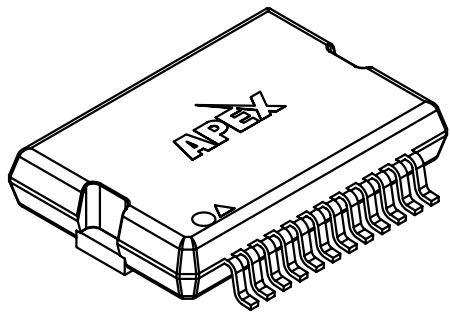
C

B

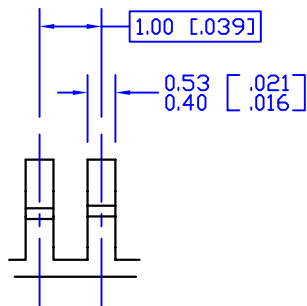
B

A

A

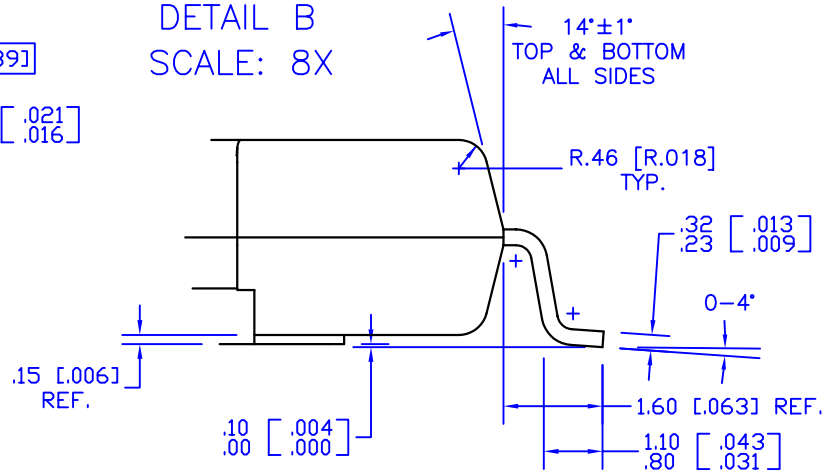


Surface Mount Layout



DETAIL A
SCALE: 8X

DETAIL B
SCALE: 8X



NOTES:

1. Dimensions are millimeters & [inches].
2. Bracketed alternate units are for reference only.
3. Dimple on lid & ESD triangle denote pin 1.
4. Pins & Heat Slug: CDA 194 copper with bismuth solder finish
5. Mold compound: MP-8000AN epoxy
6. Package weight: .086 oz. [2.44 g]
7. Suggested surface mount layout for reference only.

TOLERANCES - UNLESS OTHERWISE SPECIFIED	
.XX = ±.01 [0.254]	
.XXX = ±.005 [0.127]	
ANG. = ±.5°	



TITLE		24-PIN PSOP (JEDEC MO-166)		PACKAGE	
SUBJECT		MECHANICAL PACKAGE OUTLINE		DF	
ENG:	TECH/DRAW:	DCA	SPL	OF	FILENAME:
D-M	JCA	50141	1	1	DF
REV	DATE				
C	3/31/05				

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